

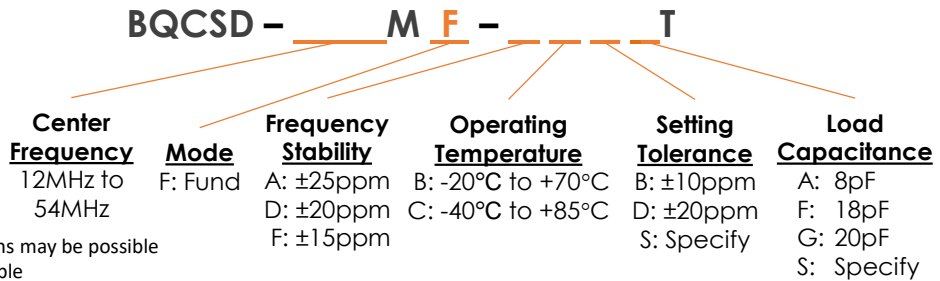
FEATURES

- ✓ SMD Construction
- ✓ Standard 4x2.5mm Package Size
- ✓ High Stability Over Temp

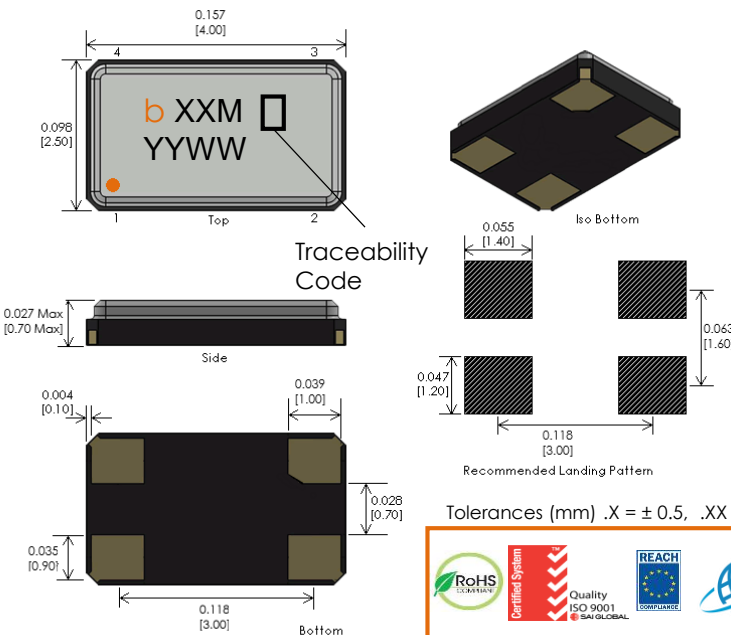
Crystals

#blileytakesyoufurther

Part Number Configuration



Physical Specifications



| PIN | FUNCTION |
|-----|----------|
| 1 | Crystal |
| 2 | Ground |
| 3 | Crystal |
| 4 | Ground |



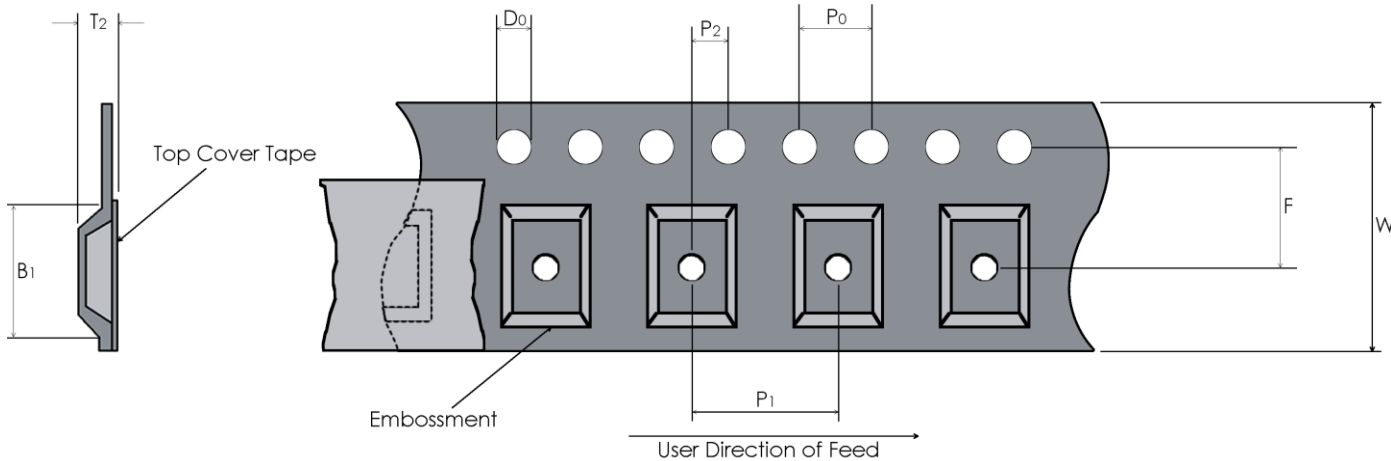
- Notes
- 1) Connection Pads: Gold(10-40 μ in.) over Nickel (100-250 μ in.)
 - 2) Weight = 1.5gms typical

Performance Specifications

| Parameter | Conditions | Min | Typ | Max | Unit |
|------------------------------------|----------------------|-------------------------|-----|------|------|
| Frequency Range | Fundamental | 12 | | 54 | MHz |
| Setting Tolerance | @ + 25°C | ±50 Max (see options) | | | ppm |
| Frequency Stability | | ±100 Max (see options) | | | ppm |
| Aging | 1 st Year | | | ±3.0 | ppm |
| Equivalent Series Resistance (max) | 12.0 – 14.9 MHz | 80 | | | Ω |
| | 15.0 – 29.9 MHz | 50 | | | Ω |
| | 30.0 – 54.0 MHz | 40 | | | Ω |
| Drive Level | | | 10 | 100 | μW |
| C0 (Shunt Capacitance) | | | | 5.0 | pF |
| CL (Load Capacitance) | Per Option (typical) | 8-32 (see options) | | | pF |
| DLD | 50nW to 100μW | | | ±10 | ppm |
| RLD | 50nW to 100μW | | | 20% | Ω |
| Operating Temp Range | See Options | -20 to +70 / -40 to +85 | | | °C |
| Storage Temp Range | | -55 | | +105 | °C |
| Sealing Method | | Seam Weld | | | |
| Moisture Sensitivity Level | | 1 | | | |

Tape and Reel

Embossed Carrier Dimensions (8mm, 12mm, 16mm, 24mm Tape Only)



| Tape Dimensions (mm) | | | | | | | | Reel Dimensions (mm) | |
|----------------------|-----|-----|-----|-----|-----|-----|-----|----------------------|--------------|
| W | F | Do | Po | P1 | P2 | B1 | T2 | Outside Dia. | Parts / Reel |
| 12 | 4.5 | 1.5 | 4.0 | 8.0 | 2.0 | 4.3 | 1.0 | 180 | 1,000 |

Recommended Reflow Profile

Reflow Profile: in accordance to IPC/JEDEC J-STD-020 (Latest Revision)

Additional Notes:

- This part has been designed for pick and place reflow soldering
- This part may be reflowed once
- This part should not be reflowed in the inverted position

Packaging

Packaging: All packaging must conform to ESD Controls detailed in ANSI/ESD S20.20 (Latest Revision)